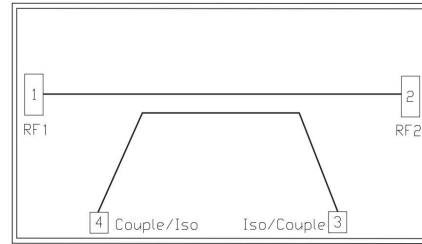


### Performance

- Frequency: 1.2~1.4GHz
- Coupling: 25dB
- Directivity: > 25dB
- Chip size: 2.2\*1.3\*0.1mm

### Function Diagram

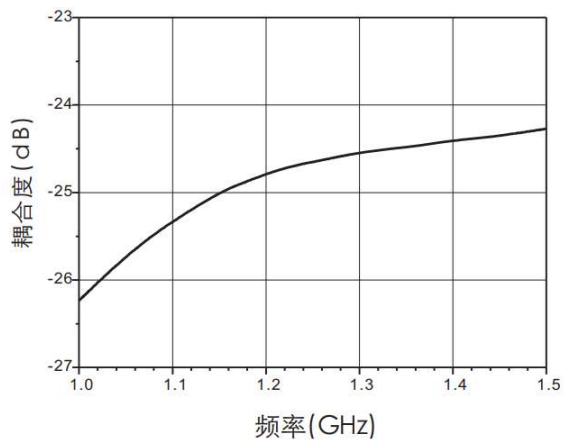


### Electrical Specifications (Ta=+25°C, 50Ω system)

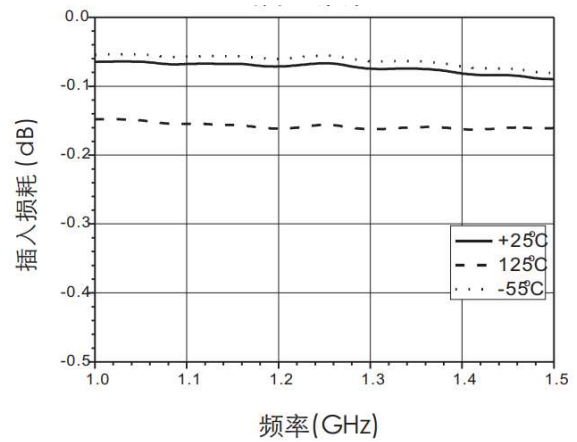
Parameter	Min	Typical	Max	Unit
Frequency Range	1.2~1.4			GHz
Coupling	24	25	25	
Insertion Loss	-	0.1	-	dB
Input Return loss	-	25	-	dB
Thru Output Return loss	-	25	-	dB
Coupling Output Return loss	-	25	-	dB

### Test Curves (Die chip + Bonding line test)

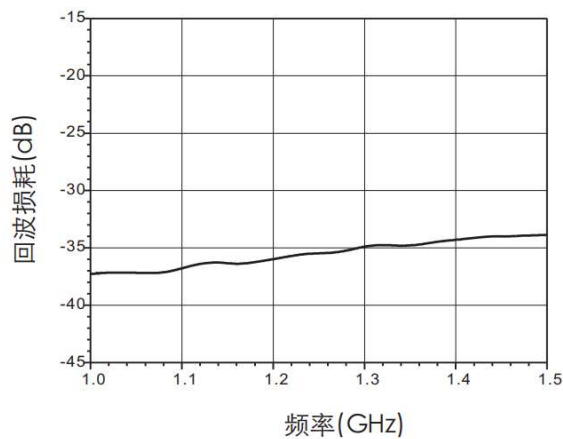
Coupling vs. Freq



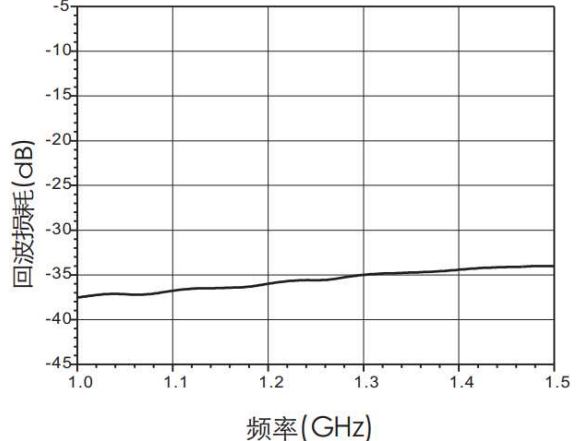
Insertion loss vs. Freq

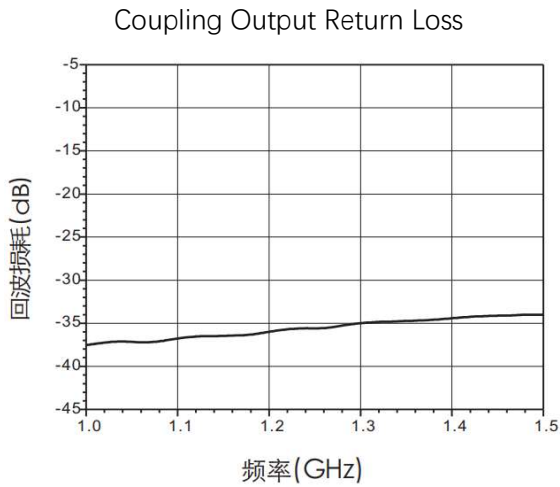


Input Return Loss vs. Freq



Thru output Return loss vs. Freq



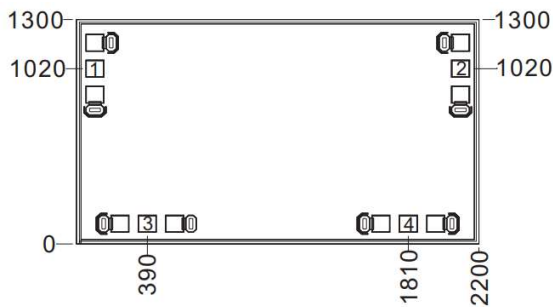


**Absolute Rating**

Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Max Input Power	50W
Static Protection (HBM)	Class 1A

ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS

**Outline Size**



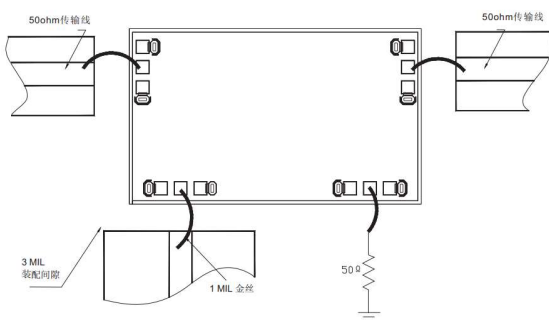
**Note:**

1. Unit:  $\mu\text{m}$
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated, Pad size:  $100 \times 100 (\mu\text{m})$
5. Don't bonding on thru holds
6. Tolerance:  $\pm 50 \mu\text{m}$

**Bonding Pads Definition**

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFOut	RF output port, 50 ohm
3,4	Couple/ISO	Choose either one as couple output port, another port connect to $50\Omega$ resistor pad

**Application (Chip left side couple output)**



**Application (Chip right side couple output)**

